



# N-Channel Reduced Q<sub>g</sub>, Fast Switching MOSFET

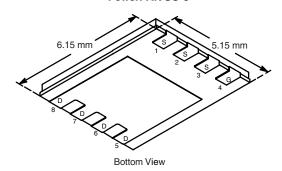
PRODUCT SUMMARY				
V <sub>DS</sub> (V)	$R_{DS(on)}\left(\Omega\right)$	I <sub>D</sub> (A)		
30	$0.0095 \text{ at V}_{GS} = 10 \text{ V}$	16		
	0.0125 at V <sub>GS</sub> = 4.5 V	16		

#### **FEATURES**

- Halogen-free According to IEC 61249-2-21 **Available**
- TrenchFET® Power MOSFET
- PWM Optimized for High Efficiency
- New Low Thermal Resistance PowerPAK® Package with Low 1.07 mm Profile
- 100 % R<sub>g</sub> Tested





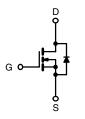


Ordering Information: Si7860ADP-T1-E3 (Lead (Pb)-free)

Si7860ADP-T1-GE3 (Lead (Pb)-free and Halogen-free)

#### **APPLICATIONS**

- **Buck Converter** 
  - High Side or Low Side
- Synchronous Rectifier
  - Secondary Rectifier



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS	$T_A = 25  ^{\circ}C$ , unles	ss otherwise r	noted			
Parameter	Symbol	10 s	Steady State	Unit		
Drain-Source Voltage		$V_{DS}$	30		V	
Gate-Source Voltage		V <sub>GS</sub>	± 20		V	
Continuous Drain Current (T <sub>.I</sub> = 150 °C) <sup>a</sup>	T <sub>A</sub> = 25 °C	I <sub>D</sub>	16	11		
Continuous Drain Current (1) = 150 °C)	T <sub>A</sub> = 70 °C		13	8		
Pulsed Drain Current		I <sub>DM</sub>	± 50		Α	
Continuous Source Current (Diode Conduction) <sup>a</sup>		I <sub>S</sub>	4.1	1.5		
Avalanche Current	L = 0.1 mH	I <sub>AS</sub>	35 60			
Single Pulse Avalanche Energy	L = 0.1 IIII1	E <sub>AS</sub>			mJ	
Marrian Parray Dissipation	T <sub>A</sub> = 25 °C	P <sub>D</sub>	4.8	1.8	W	
Maximum Power Dissipation <sup>a</sup>	T <sub>A</sub> = 70 °C		3.1	1.1		
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150		°C	
Soldering Recommendations (Peak Temperature) <sup>b, c</sup>			260			

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
Manifestor Investigation to Ambient (MOCETT)	t ≤ 10 s	- R <sub>thJA</sub>	21	26	°C/W
Maximum Junction-to-Ambient (MOSFET) <sup>a</sup>	Steady State		56	70	
Maximum Junction-to-Case (Drain)	Steady State	$R_{thJC}$	1.9	2.5	

- a. Surface Mounted on 1" x 1" FR4 board.
- b. See Solder Profile (http://www.vishay.com/ppg?73257). The PowerPAK SO-8 is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.
- c. Rework Conditions: manual soldering with a soldering iron is not recommended for leadless components.

## Vishay Siliconix



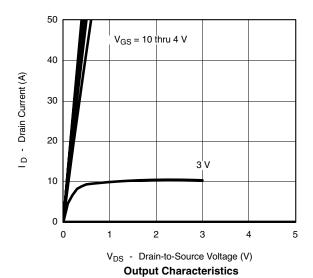
<b>MOSFET SPECIFICATIONS</b> $T_J = 25$ °C, unless otherwise noted								
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit		
Static	•		•	•				
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1.0		3.0	V		
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA		
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}$			1	μА		
Zero Gale Vollage Dialii Current		$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 70 ^{\circ}\text{C}$			5			
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	40			Α		
Durin Course Co Chata Daristana a	B / .	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 16 A		0.0079	0.0095	Ω		
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	$V_{GS} = 4.5 \text{ V}, I_D = 14 \text{ A}$		0.0105	0.0125			
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 16 A		60		S		
Diode Forward Voltage <sup>a</sup>	$V_{SD}$	I <sub>S</sub> = 3 A, V <sub>GS</sub> = 0 V		0.70	1.1	V		
Dynamic <sup>b</sup>			<u>'</u>	1				
Total Gate Charge	$Q_g$			13	18			
Gate-Source Charge	$Q_{gs}$	$V_{DS} = 15 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 16 \text{ A}$		5		nC		
Gate-Drain Charge	$Q_{gd}$			4.0				
Gate Resistance	$R_g$		0.5	1.7	3.2	Ω		
Turn-On Delay Time	t <sub>d(on)</sub>			18	27			
Rise Time	t <sub>r</sub>	$V_{DD}$ = 15 V, $R_L$ = 15 $\Omega$		12	18			
Turn-Off Delay Time	t <sub>d(off)</sub>	$\text{I}_\text{D}\cong\text{1 A, V}_\text{GEN}=\text{10 V, R}_g=\text{6}~\Omega$		46	70	ns		
Fall Time	t <sub>f</sub>			19	30			
Source-Drain Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = 3 A, dI/dt = 100 A/μs		40	70			

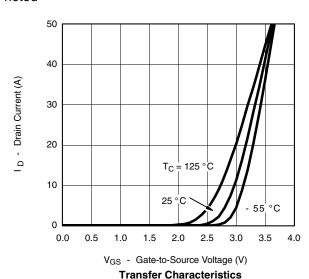
#### Notes:

- a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



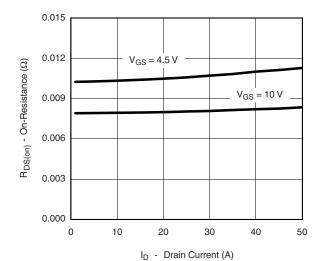




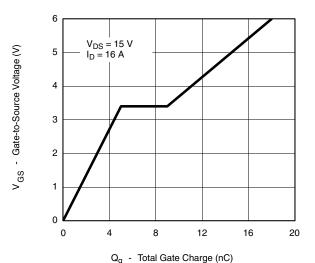




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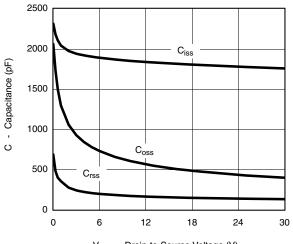
On-Resistance vs. Drain Current



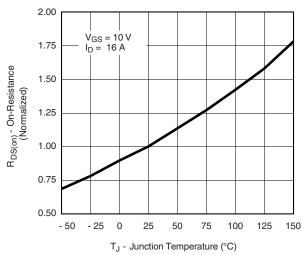
60 T<sub>J</sub> = 150 °C 10 T<sub>J</sub> = 25 °C 0.00 0.2 0.4 0.6 1.0 1.2 0.8

**Gate Charge** 

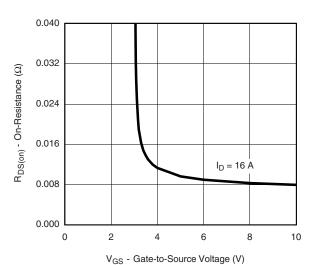
V<sub>SD</sub> - Source-to-Drain Voltage (V) Source-Drain Diode Forward Voltage



V<sub>DS</sub> - Drain-to-Source Voltage (V) Capacitance



On-Resistance vs. Junction Temperature



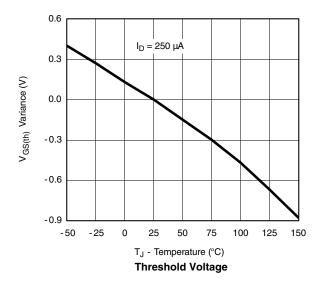
On-Resistance vs. Gate-to-Source Voltage

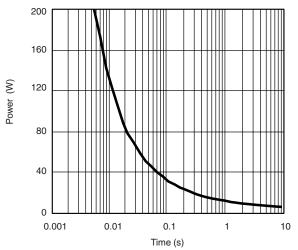
Is - Source Current (A)

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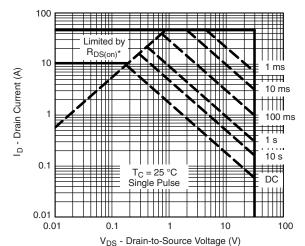
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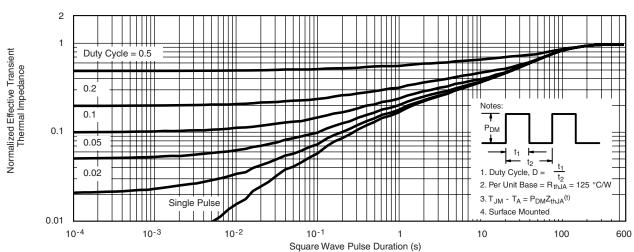


Single Pulse Power, Junction-to-Ambient



\*  $V_{GS}$  > minimum  $V_{GS}$  at which  $R_{DS(on)}$  is specified

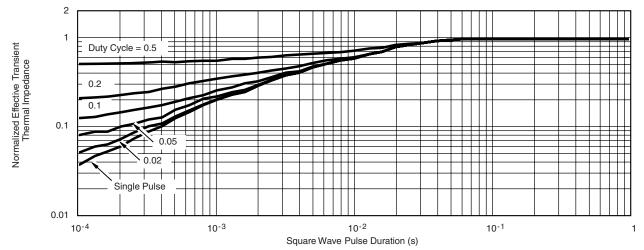
#### Safe Operating Area, Junction-to-Case



Normalized Thermal Transient Impedance, Junction-to-Ambient



#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Case

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